News Release

Amkor Offers Optical Package Solutions for Multiple Applications

TEMPE, Ariz., December 13, 2018 — Amkor Technology, Inc. (Nasdaq: AMKR), a leading provider of outsourced semiconductor assembly and test (OSAT) services, today announced the extension of its MEMS and Sensor package platforms to address the growing optical market. The new optical package platforms are derivatives of our successful ChipArray® BGA and *Micro*LeadFrame® product families and can be used for many applications including LIDAR, fingerprint sensing, ambient light sensing and 3D facial recognition.

“Amkor has over 25 years of experience manufacturing and testing MEMS and Sensor devices for automotive, communications and consumer applications” said John Donaghey, Corporate Vice President, Amkor Technology. “We are excited to extend our high-volume MEMS and Sensor package platforms to address optical market requirements. This allows our customers to bring their solutions to market quickly without sacrificing performance.”

Amkor’s factories are IATF16949 certified and have the ability to meet the rigorous requirements of the AEC-Q100 specification. Full turnkey optical MEMS and Sensor solutions from Amkor include design, assembly and test. To learn more about Amkor’s capabilities in Optical MEMS and Sensor packaging, visit www.amkor.com/technology/optical-sensors/.

About Amkor Technology, Inc.

Amkor Technology, Inc. is one of the world’s largest providers of outsourced semiconductor packaging and test services. Founded in 1968, Amkor pioneered the outsourcing of IC packaging and test, and is now a strategic manufacturing partner for more than 250 of the world’s leading semiconductor companies, foundries and electronics OEMs. Amkor’s operating base includes 11 million square feet of floor space with production facilities, product development centers, and sales and support offices located in key electronics manufacturing regions in Asia, Europe and the U.S. For more information, visit www.amkor.com.

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